IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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BEFORE THE PATENT TRIAL AND APPEAL BOARD

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Taiwan Semiconductor Manufacturing Company Ltd.,

Petitioner,

v.

Advanced Integrated Circuit Process LLC,

Patent Owner.

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IPR2025-01210

U.S. Patent No. 7,632,751

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PETITIONER'S UPDATED EXHIBIT LIST

UPDATED EXHIBIT LIST

Exhibit No.	Description	Filed	Served
1001	U.S. Patent No. 7,632,751	X	X
1002	File History of U.S. Patent No. 7,632,751 ("'751 File History")	X	X
1003	Declaration of Dr. Reinhold Dauskardt	X	X
1004	U.S. Patent Publication No. 2003/0116852 to Watanabe et al. ("Watanabe")	X	X
1005	U.S. Patent Publication No. 2004/0113238 to Hasunuma et al. ("Hasunuma")	X	X
1006	U.S. Patent Publication No. 2001/0019180 to Aoyagi et al. ("Aoyagi")	X	X
1007	U.S. Patent No. 6,717,267 to Kunikiyo ("Kunikiyo")	X	X
1008	U.S. Patent No. 5,250,465 to Iizuka et al. ("Iizuka")	X	X
1009	U.S. Patent Publication No. 2004/0173905 to Kamoshima et al. ("Kamoshima")	X	X
1010	JP2002299437 ("Fukazawa") and Certified Translation of Fukazawa with Certification of Translation	X	X
1011	U.S. Patent No. 7,042,099 to Kurashima ("Kurashima")	X	X
1012	P. Andricacos, "Copper On-Chip Interconnections," *Interface*, *The Electrochemical Society*, pp. 32-37, 1999	X	X

Exhibit No.	Description	Filed	Served
1013	U.S. Patent No. 5,885,857 to Yamaha et al. ("Yamaha")	X	X
1014	U.S. Patent Publication No. 2003/0005399 to Igarashi ("Igarashi")	X	X
1015	U.S. Patent No. 6,717,268 to Hau-Riege ("Hau-Riege")	X	X
1016	U.S. Patent No. 6,468,894 to Yang ("Yang")	X	X
1017	U.S. Patent No. 6,022,808 to Nogami ("Nogami")	X	X
1018	Reserved		
1019	Kaanta et al., "Dual Damascene: A ULSI Wiring Technology," *VMIC Conference*, IEEE, Jun. 11-12, 1991, pp. 144-152	X	X
1020	U.S. Patent No. 5,032,890 to Ushiku ("Ushiku")	X	X
1021	Reserved		
1022	U.S. Patent No. 6,582,976 to Watanabe ("Watanabe'976")	X	X
1023	S. Middleman et al., *Process Engineering Analysis in Semiconductor Device Fabrication*, pp. 260-61 (excerpted), McGraw-Hill, 1993 ("Middleman")	X	X
1024	U.S. Patent No. 6,156,660 to Liu et al. ("Liu")	X	X
1025	U.S. Patent No. 5,798,298 to Yang ("Yang 2")	X	X

Exhibit No.	Description	Filed	Served
1026	T. I. Bao et al., "90 nm Generation Cu/CVD Low-k (k < 2.5) Interconnect Technology," *Digest. International Electron Devices Meeting*, San Francisco, CA, USA, 2002, pp. 583-586	X	X
1027	A. Loke, "Process Integration Issues of Low-Permittivity Dielectrics With Copper for High-Performance Interconnects, Dissertation," Stanford University (1999)	X	X
1028	K.N. Tu, "Recent advances on electromigration in very-large- scale-integration of interconnects," *Applied Physics Review – Focused Review*, *Journal of Applied Physics*, Vol. 94, No. 9, pp. 5451-5473 (November 1, 2003)	X	X
1029	T. C. Huang, et al., "Numerical Modeling and Characterization of the Stress Migration Behaviour Upon Various 90 nanometer Cu/Low k Interconnects," *Proceedings of the IEEE 2003 International Interconnect Technology Conference (Cat. No.03TH8695)*, Burlingame, CA, USA, 2003 (added to IEEE Xplore 8-11-2003), pp. 207-209	X	X
1030	Reserved		
1031	Reserved		
1032	JP2000012688 to Nasu ("Nasu") and Certified Translation of Nasu with Certification of Translation	X	X
1033	U.S. Patent Publication No. 2001/0030365 to Otsuka et al. ("Otsuka")	X	X

Exhibit No.	Description	Filed	Served
1034	Wolf, Stanley, *Silicon Processing for the VLSI Era: Deep- Submicron Process Technology*, Lattice Press, 2002 (excerpted) ("Wolf")	X	X
1035	U.S. Patent No. 6,858,944 to Huang et al. ("Huang")	X	X
1036	Reserved		
1037	Reserved		
1038	U.S. Patent No. 6,215,189 to Toyoda et al. ("Toyoda")	X	X
1039	U.S. Patent No. 6,238,850 to Bula et al. ("Bula")	X	X
1040	STIPULATION: 7-31-2025 Letter from K. Wheatley (counsel for TSMC) to J. Nelson et al. (counsel for AICP)	X	X
1041	Patent Assignment Record from Nuvoton Technology Corp. Japan to Advanced Integrated Circuit Process LLC, Reel: 068118 Frame: 0314-0317, United States Patent and Trademark Office (July 30, 2024)	X	X
1042	United States District Courts – National Judicial Caseload Profile, 12-Month Period Ending Mar. 31, 2025, U.S. Courts (2025), available at https://www.uscourts.gov/sites/default/files/document/fcms_na_distprofile0331.2025.pdf	X	X
1043	Summary of Judge Gilstrap Patent Trials Between October 22, 2024 and October 22, 2025	X	X
1044	Docket for 2:23-cv-00274 (E.D. Tex.)	X	X
1045	Docket for 2:23-cv-0379 (E.D. Tex.)	X	X

Exhibit No.	Description	Filed	Served
1046	Docket for 2:24-cv-00034 (E.D. Tex.)	X	X
1047	Docket for 2:24-cv-00047 (E.D. Tex.)	X	X
1048	Docket for 2:24-cv-00049 (E.D. Tex.)	X	X
1049	Jeremy Bowman, Nasdaq, This 1 Number May Ensure TSMC's Market Dominance, The Motley Fool (Aug. 17, 2024) (last visited October 22, 2025), available at https://www.nasdaq.com/articles/1-number-may-ensure-tsmcs-market-dominance	X	X
1050	CNBC Transcript: United States Commerce Secretary Howard Lutnick Speaks with CNBC's Brian Sullivan on "The Exchange" Today, CNBC (Apr. 29. 2025) (last visited October 22, 2025), available at https://www.cnbc.com/2025/04/29/cnbc-transcript-united-states-commerce-secretary-howard-lutnick-speaks-with-cnbcs-brian-sullivan-on-the-exchange-today.html	X	X
1051	Trump on China Putting - America First (Robert C. O'Brien editor)	X	X
1052	Remarks: Donald Trump Announces an Economic Investment in the United States - March 3, 2025, available at https://rollcall.com/factbase/trump/transcript/donald-trump-remarks-economic-investment-united-states-march-3-2025/#2	X	X
1053	Speech: Donald Trump Addresses an Republican Dinner in Washington - April 8, 2025, available at https://rollcall.com/factbase/trump/transcript/donald-trump-speech-nrcc-republican-dinner-april-8-	X	X

Exhibit No.	Description	Filed	Served
	2025/#161		
1054	Microchip USA, How Military Tensions Are Driving the Next Semiconductor Chip Race (July 16, 2025) (last visited Aug. 12, 2025), available at https://www.microchipusa.com/industry-news/how-military-tensions-are-driving-the-next-semiconductor-chip-race?srsltid=AfmBOopQdXXTBoOGl_bluj9BHhwBFREsja-0SrRhCUKPHwTlW98FCBKI	X	X
1055	Another Historic Investment Secured Under President Trump, Articles, The White House (Mar. 3, 2025) (last visited July 14, 2025), available at https://www.whitehouse.gov/articles/2025/03/another-historic-investment-secured-under-president-trump/	X	X
1056	Sujai Shivakumar and Charles Wessner, Semiconductors and National Defense: What Are the Stakes?, Center for Strategic International Studies (June 8, 2022) (last visited July 14, 2025), available at https://www.csis.org/analysis/ semiconductors-and-national-defense-what-are-stakes	X	X
1057	U.S., Taiwan, and Semiconductors: A Critical Supply Chain Partnership, Final Report, Project 2049 Institute (US-Taiwan Business Counsel June 21, 2023)	X	X
1058	Eric Lee, How Taiwan Underwrites the US Defense Industrial Complex, The Diplomat (Nov. 9, 2021) (last visited July 14, 2025), available at https://thediplomat.com/2021/11/how-taiwan-underwrites-the-us-defense-industrial-complex/	X	X
1059	Reserved		

Exhibit No.	Description	Filed	Served
1060	Reverved		
1061	Reserved		
1062	Reserved		
1063	Silvia Pellegrino, What is TSMC?, Tech Monitor (Jan. 2, 2023) (last visited July 14, 2025), available at https://www.techmonitor.ai/what-is/what-is-tsmc/?cf-view	X	X
1064	Patent Owner's Response and Objections to Petitioner's First Request for Production of Documents (Contains Material Marked Highly Confidential – Attorneys' Eyes Only) FILED UNDER SEAL	X	X
1065	Reserved		
1066	Reserved		
1067	U.S. Patent No. 7,067,919 to Watanabe et al. ("Watanabe'919")	X	X
1068	U.S. Patent No. 6,958,542 to Hasunuma et al. ("Hasunuma'542")	X	X
1069	JP4047324 file wrapper – excerpts and Certified Translation of excerpts and Certification of Translation	X	X
1070	16/12nm Technology	X	X
1071	Prosecution History 7,439,623	X	X
1072	Petition for *Inter Partes* Review IPR2025-01212	X	X
1073	Removing Barriers to American Leadership in	X	X

Exhibit No.	Description	Filed	Served
	Artificial Intelligence, Presidential Actions, The White House (Jan. 23, 2025) (last visited July 14, 2025), available at https://www.whitehouse.gov/presidentialactions/2025/01/removing-barriers-to-american-leadership-inartificial-intelligence/		
1074	Office of Science and Technology Policy, Executive Office of the President of the United States, Winning the Race: America's AI Action Plan (July 2025)	X	X
1075	U.S.-China Economic and Security Review Commission, 2024 Report to Congress of the U.S.-China Economic and Security Review Commission, 118 Cong., 2d Sess. (2024)	X	X
1076	TSMC Expands Collaboration with Ansys by Integrating AI Technology to Accelerate 3D-IC Design, Ansys (Sept. 25, 2024) (last visited July 14, 2025), available at https://investors.ansys.com/news-releases/news-releasedetails/tsmc-expands-collaboration-ansys-integrating-ai-technology	X	X
1077	Cadence and TSMC Advance AI and 3D-IC Chip Design with Certified Design Solutions for TSMC's A16 and N2P Process Technologies, Cadence (Apr. 23, 2025) (last visited July 14, 2025), available at https://www.cadence.com/en_US/home/company/newsroom/pressreleases/pr/2025/cadence-and-tsmc-advance-ai-and-3d-ic-chipdesign-with-certified.html	X	X
1078	Silent Giant TSMC Returns to the Peak of its Powers as the AI Boom Continues, Yahoo! finance (June 12, 2025), available at https://finance.yahoo.com/news/silent-giant-tsmc-returns-peak230300515.html?guccounter=1&guce_referrer=a	X	X

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	HR0cHM6Ly93d3 cuZ29vZ2xlLmNvbS8&guce_referrer_sig=AQAAA GbNeBi6fbz4 U1LAPZACoSOpXFKhZ2d8Aeym1OTBUscShGSw m5cDQL_KD bidYk16TkPx7YtIzsB2YbOGeGdO4PchwSBFYrk3f Tg3HWrMVsPIL1q7mWa7ZR5e6BG0tbKASjEzPE-8raiT0KakQ2cXTjpdVs4xTGUvCoXUGlVbDT		
1079	Alex He, In the Global AI Chips Race, China Is Playing Catch-Up (September 18, 2024)	X	X
1080	Jeff Klearman, Decoding TSMC's Contribution to the AI and 5G Ecosystem (November 20, 2024), available at https://graniteshares.com/institutional/us/en-us/research/decoding-tsmc-s-contribution-to-the-ai-and-5g-ecosystem	X	X
1081	Charlotte Trueman, Mayo Clinic to use Cerebras chips for medical AI models (January 9, 2024), available at https://www.datacenterdynamics.com/en/news/mayo-clinic-to-use-cerebas-chips-for-medical-ai-models/	X	X
1082	Vishal Subbiah, A Big Chip for Big Science: Watching the COVID-19 Virus in Action – Cerebras (December 14, 2021), available at https://www.cerebras.ai/blog/a-big-chip-for-big-science-watching-the-covid-19-virus-in-action	X	X

CERTIFICATE OF SERVICE

The undersigned hereby certifies that on October 28, 2025 a true and correct copy of **EXHIBITS 1041 – 1058, 1063 – 1064, and 1067 – 1082** and **PETITIONER'S UPDATED EXHIBIT LIST** was served in its entirety on the Patent Owner to the email addresses below:

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